

Patent

Customer No.: 3156
Docket No.: 10665-US-PA
Application No.: 10/605,305

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Ho et al.
Application No. : 10/605,305
Filed : 2003/09/22
For : BUMP PROCESS FOR FLIP CHIP PACKAGE
Art Unit : 2829
Examiner : GEYER, SCOTT B

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REQUEST FOR CORRECTION TO PUBLICATION OF APPLICATION
VIA FACSIMILE ONLY (002-1-703-308-5065)

U.S. Patent and Trademark Office
Office of Public Records,
Alexandria, VA 22313-1450

Dear Sir/Madam,

We are writing in relation to the Notice of Publication of Application of the above-identified application.

After a review of the publication of the subject application, it is noticed that apart from the first page of the publication, the rest of the publication of the application is incorrect and verified to be that of U.S. Patent No. 09/844,224, filed on April 27, 2001.

We respectfully request the U.S. Patent and Trademark Office to replace the incorrect publication with the one we previously submitted soon.

Thank you so much for your attention. Please do not hesitate to contact us if you have any questions regarding this matter.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: April 27, 2005

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